承認書

SPECIFICATION FOR APPROVAL

| CUSTOMER: | |
|---------------|---------------------|
| CUSTOMER P/N | |
| PART NO: | |
| DESCRIPTION: | SMD POWER INDUCTORS |
| PRODUCTS NO: | BCRH104R-150M |
| PRODUCTS REV: | 01 |
| DATE: | 2018-6-11 |

| PURCHASER CONFIRMED. | | | | | | |
|----------------------|----------|----------|--|--|--|--|
| APPROVAL BY | СНЕСК ВҮ | DRAWN BY | | | | |
| | | | | | | |
| | | | | | | |
| REMARK | | | | | | |

| PROVIDER ENGINEER DEPT. | | | | | |
|-------------------------|--|-----------|--|--|--|
| APPROVAL BY CHECK BY | | | | | |
| | | chenlinli | | | |

誠陽實業有限公司



TAIWAN CHENG YANG COMPONENT CORP

2F-1, NO. 176, Chine-Yi Road., Zhonghe District, New Taipei City, TAIWAN(R.O.C) 新北市中和區建一路 176 號 2 樓之一

TAIPEI OFF ICE

POSTAL CODE: 23500

TEL NO.:+886-2-8228-0930 FAX NO.:+886-2-8228-0929 E-mail:h21803@ms29.hinet.net



寶誠電子有限公司

ZHUHAI BAO CHENG ELECTRONICSCO.,LTD

Guan Tang Industrial Park, Tang Jia Wan Town, Zhuhai City, Guangdong Province, CHINA中國廣東省珠海市塘家灣鎮官塘工業區

CHINA FACTORY

POSTAL CODE: 519085

TEL NO:86-756-3383187 FAX NO:86-756-3380704 E-mail: baocheng@baocheng.biz



昆山誠陽電子有限公司

KUNSHAN CHENG YANG ELECTRONICSCO.,LTDP

CHINA FACTORY

Qiang-An Road., High-Tech. Industrial Park, Kunshan City, Jiangsu Province, China

江蘇省昆山市高科技工業園區強安路 35 號

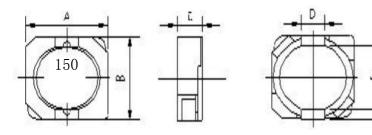
POSTAL CODE: 215300

 $TEL\ NO: 86-512-57823500\ FAX\ NO: 86-512-57823503\ E-mail: kscy@taiwan-chengyang.com.tw$

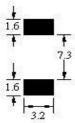
TEST DATADIMENSION&ELECTRIC CHARACTER

| CUSTOMER: | | PART NO.: | |
|--------------|--------------|------------|---------------|
| DESCRIPTION: | SMD INDUCTOR | SERIES NO: | BCRH104R-150M |

1.MECHANICAL DIMENSION



².RECOMMEND LAND PATTERN DIMENSIONS



UNIT:mm

| A | 10.3MAX | |
|---|---------------------|--|
| В | 10.5MAX | |
| С | 4. OMAX | |
| D | 3. 0 <u>+</u> 0. 1 | |
| Е | 7. 7 <u>+</u> 0. 3 | |
| F | 1. 2 <u>+</u> 0. 15 | |
| G | | |
| Н | | |
| Ι | | |

3.SEPCIFICATIONS

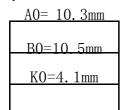
| Part Number | L | R _{dc} (m | nOHM) | Heat Rating Current DC | Saturation Current DC Amps. 1dc(A) | |
|---------------|----------------|--------------------|-------|------------------------|---------------------------------------|--|
| | Inductance | m : 1 | м | Amps. Idc(A) | | |
| | (uH) @ (OA) | Typical | Max | Typical | Typical | |
| BCRH104R-150M | 15. 0 | 44 | 50 | 3. 1 | 3. 6 | |

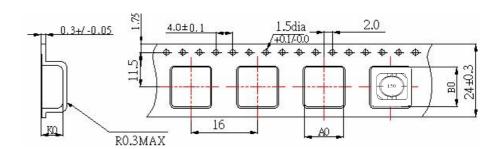
- (1). All test data is referenced to 25°C ambient.
- (2). Operating Tenperature Rangr-30°C to +100°C.
- (3). DC current(A)that will cause an approximate \triangle T of 40°C.
- (4). DC current (A) that will cause Lo to drop approximately 35%.
- (5). The part temperature (ambient+temp rise) should not exceed 100℃ under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and oter acoting provisions all affect the part temperature part temperature should be verified in the end application.

4.PACKAGING INFORMATION

paets are packaged on 13"reels

800 parts per reel.





APPROVED BY: CHECKED BY: DRAWN BY:chenlinli

ZHUHAI BAOCHENG ELECTRONICS CO., LTD TEST DATA FOR PREPRODUCTION SAMPLE

| CUSTOMER: | | | CUSTOM | ER P/N: | | | CUSTO | MER REV | ': | TEST DATE | :2018-6-11 |
|-------------------------|--------|----------------------------------|--------|---------|---------------|---|--------|---------|------------|-----------|------------|
| PART NAME: SMD INDUCTOR | | BC PART NO: BCRH104R-150M BC REV | | | EV: QUANTITY: | | :10PCS | | | | |
| TEST ITEM | A | В | С | D | Е | F | G | Н | I | J | K |
| SPEC. | 10.3 | 10. 5 | 4. 0 | | | | | | | | |
| of Lo. | MAX | MAX | MAX | | | | | | | | |
| 01 | 10.00 | 10. 25 | 3. 81 | | | | | | | | |
| 02 | 9. 99 | 10. 24 | 3. 79 | | | | | | | | |
| 03 | 10.00 | 10. 28 | 3. 83 | | | | | | | | |
| 04 | 10.03 | 10. 29 | 3. 82 | | | | | | | | |
| 05 | 10. 19 | 10. 31 | 3. 82 | | | | | | | | |
| 06 | 10. 18 | 10. 38 | 3. 79 | | | | | | | | |
| 07 | 10. 05 | 10. 29 | 3. 83 | | | | | | | | |
| 08 | 10.06 | 10. 19 | 3. 81 | | | | | | | | |
| 09 | 10. 18 | 10. 32 | 3. 86 | | | | | | | | |
| 10 | 10.09 | 10. 27 | 3. 84 | | | | | | | | |
| 11 | | | | | | | | | | | |
| 12 | | | | | | | | | | | |
| 13 | | | | | | | | | | | |
| 14 | | | | | | | | | | | |
| 15 | | | | | | | | | | | |
| \overline{X} | 10.08 | 10. 28 | 3. 82 | | | | | | | | |
| σ | 0.075 | 0.048 | 0.020 | | | | | | | | |
| Cpk | 0.99 | 1.50 | 2. 93 | | | | | | | | |
| | | | | | | | | | | | |
| APPROVED BY | | | | CHECKE | ED BY | | | PF | REPARED B' | Y | |
| | | | | | | | c. | henlin | li | | |

ZHUHAI BAOCHENG ELECTRONICS CO., LTD TEST DATA FOR PREPRODUCTION SAMPLE

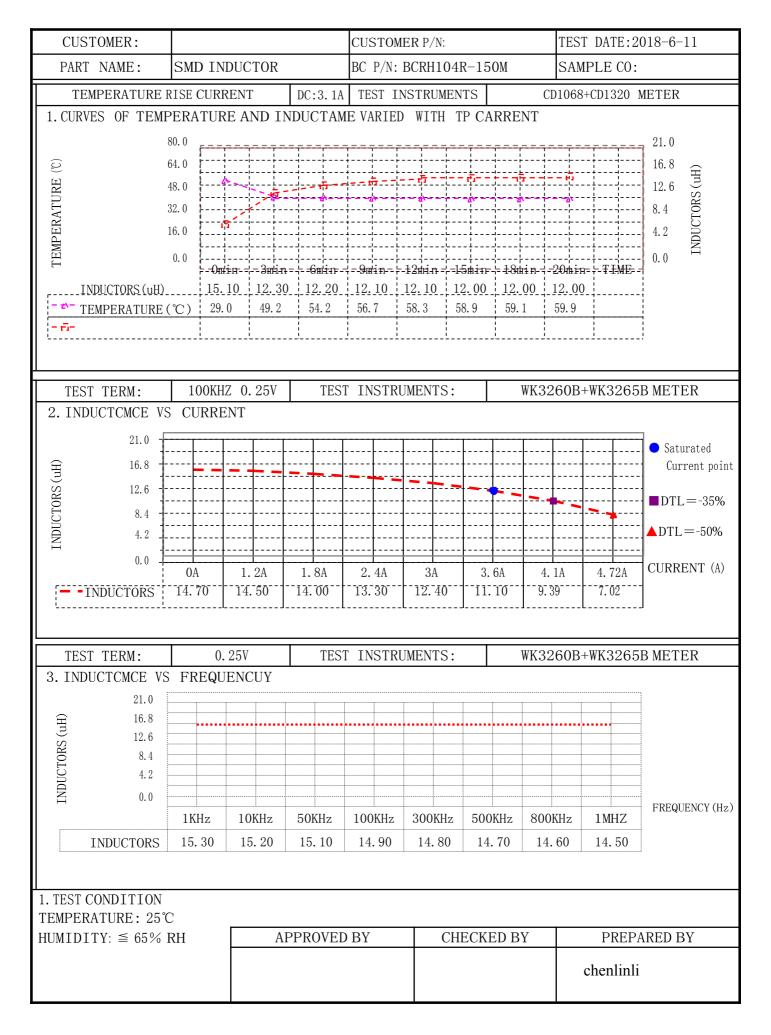
| CUSTOMER | | CUSTOMER P/N: | | CUSTOMER REV: | TEST DATE:2018-6-11 | |
|-------------------------|----------------------|---------------------|----------------|---------------|---------------------|--|
| PART NAME: SMD INDUCTOR | | BC PART NO: BCRH10 | 04R-150M | BC REV: | QUANTITY: 10PCS | |
| TEST ITEM | L (0A) | L(3.6A)/L(0A)100% | DCR (S-F) | | | |
| TEST CONDITION | 100KHZ 0. 25V | | | | | |
| SPEC. | 15uH <u>+</u> 20% | = 65% AT DC 3.6A | $50\mathrm{m}$ | | | |
| 01 | 14. 36 | 73% | 43.66 | | | |
| 02 | 14. 22 | 78% | 44.52 | | | |
| 03 | 15.84 | 80% | 45. 78 | | | |
| 04 | 14.67 | 78% | 44. 23 | | | |
| 05 | 15.06 | 75% | 43. 43 | | | |
| 06 | 14.05 | 89% | 42.89 | | | |
| 07 | 15.85 | 80% | 42. 56 | | | |
| 08 | 14.82 | 78% | 44.83 | | | |
| 09 | 14.75 | 79% | 45. 18 | | | |
| 10 | 14. 32 | 73% | 43.81 | | | |
| 11 | | | | | | |
| 12 | | | | | | |
| 13 | | | | | | |
| 14 | | | | | | |
| 15 | | | | | | |
| \overline{X} | 14. 79 | | 44. 09 | | | |
| σ | 0.600 | | 0. 963 | | | |
| Cpk | 2.39 | | 2.05 | | | |

- 1. TEST INSTRUMENTS:
- \square HP-4284A METER
- ■HP-4285A METER
- □HP-4191A METER
- □VR116+VR7220 METER
- □CH-3200 METER
- □CH-310 METER
- □CH-3305 METER
- ■CD1068+CD1320 METER
- UR113+VR712+R712 METER
- \square WK3260B+WK3265B METER
- □VR562 METER
- ■CH-502B DCR METER
- 2. CONDITION

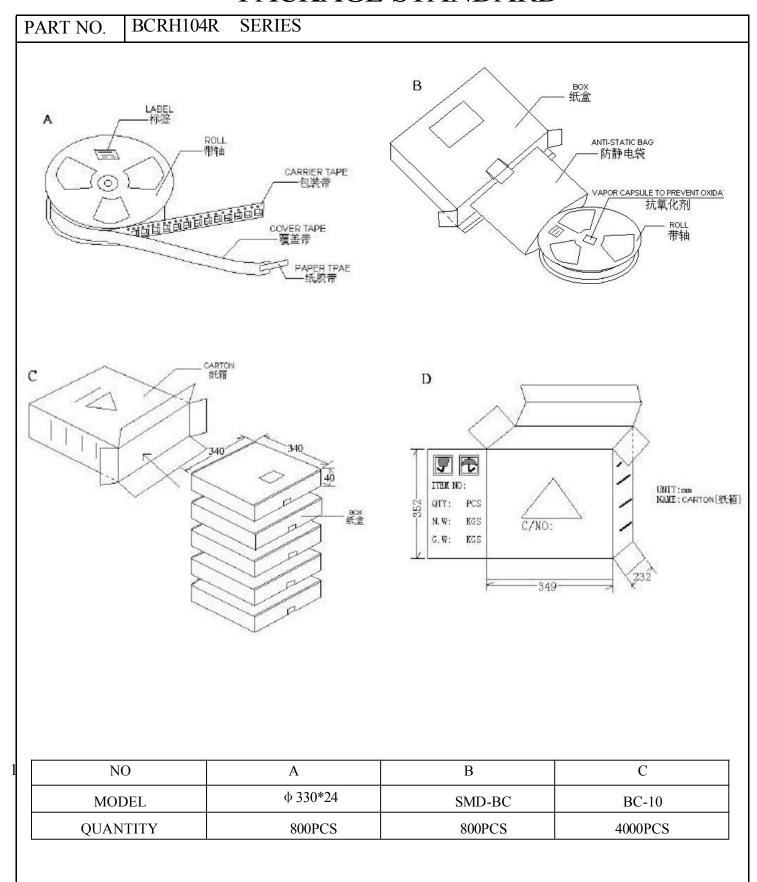
TEMPERATURE: 25℃ HUMIDITY: 65%RH

| APPROVED BY | CHECKED BY | PREPARED BY |
|-------------|------------|-------------|
| | | chenlinli |

ELECTRONICS CHARACTER TEST CHART



PACKAGE STANDARD



| ■GENERAL CHAR | P.1 | | | |
|------------------------|---|--|--|--|
| Operation Temperature | -30°C to +100°C (Includes temperature when the coil is heated) | | | |
| External Appearance | On visual inspection, the coil has no external defects. | | | |
| Solder Ability Test | 1. More than 90% of terminal electrode should be covered with solder. ■ After fluxing, component shall be dipped in a melted. ■ Solder: bath at 230°C±5°C for 5±0.5 150°C second 5±0.5 second | | | |
| Solder Heat Resistance | 1. Components should have not evidence of electrical and mechanical damage. 2. Inductance: within±10% of initial value. 3. Impedance: within±30% of initial value. Preheat:150±5°C 60seconds. Solder temperature: 260±5°C. Flux: rosin. Dip time:10±0.5seconds. | | | |
| Terminal Strength | After soldering of X,Y withstanding at below conditions .The terminal should not Peel off. (Refer to figure at below) • 5N:60sec. BC Series, BCB Series, BCDB Series, BCEI Series BCEP Series, BCH Series, BCMD Series, BCMS Series, BCPS Series BCR Series, BCRH Series, BCRHB Series, BCX Series, BCIHP Series, BCLQ72, BCRM135, BCPH73, BCC5D23, BCHP1210. • 10N:10sec. BC73, BC75, BC4020FH, BC74B. • 15N:10sec. BC104, BC105, BC105B, BC108, BC5022FH. • 20N:10sec. BCR125B. | | | |
| Insulating Resistance | Over 100MO at 100V D.C. between coil and core. | | | |
| Dielectric Strength | No dielectric breakdown at 100V D.C. for 1 minute between coil and core. | | | |
| Vibration Resistance | Inductance deviation within ±3% after vibration for 1 hour. In each of three orientations at Sweep vibration (10~55~10HZ) with 1.5mmP-P amplitudes. | | | |
| Shock Resistance | Inductance deviation within ±3% after being dropped once with 981m/s ² (100G) shock Attitude upon a rubber block method shock testing machine, in three different orientations | | | |
| Application Natica/Hay | 110 | | | |

■ Application Notice/Handling

1. Storage Conditions

To maintain the solder ability of terminal electrodes:

- (1) Temperature and humidity conditions: less than 40°C and 70% RH.
- (2) Products should be used within 6 months.
- (3) The packaging material should be kept where no chlorine or sulfur exists in the air.

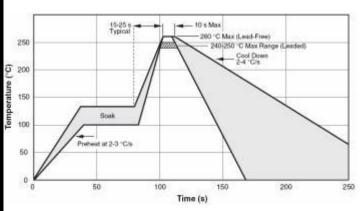
2. Handling

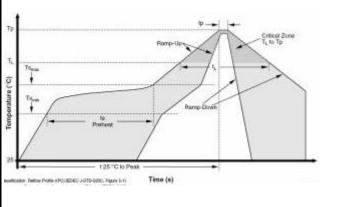
- (1) Do not touch the electrodes (soldering terminals) with fingers as this may lead to deterioration of solderability.
- (2) The use of tweezers or vacuum pick-ups is strongly recommended for individual components.
- (3) Bulk handling should ensure that abrasion and mechanical shock are minimized.

■THE CONDITION OF REFLOW(RECOMMENDATION)

TYPICAL WAVE SOLDER PROFILE FOR LEADED AND LEAD-FREE THROUGH-HOLE PACKAGES

TYPICAL IR REFLOW PROFILE FOR LEADED AND LEAD-FREE SURFACE MOUNT PACKAGES





IPC/JEDEC J-STD-020C, Figure 5-1

| ii civibble v bib v2ve, i iguie s i | | |
|--|------------------------------------|------------------------------------|
| Profile Feature | Sn-Pb Eutectic Assembly | Pb-Free Assembly |
| Average Ramp-Up Rate (Ts _{max} to Tp) | 3 °C/second max. | 3 °C/second max. |
| Preheat ± Temperature Min (Ts _{min}) ± Temperature Max (Ts _{max}) ± Time (ts _{min} to ts _{max}) | 100 °C 150 °C 60-120 seconds | 150 °C 200 °C 60-180 seconds |
| Time maintained above: \pm Temperature (T_L) \pm Time (t_L) | 183 °C 60-150 seconds | 217 °C 60-150 seconds |
| Peak/Classification Temperature (Tp) | See Table 4.1 | See Table 4.2 |
| Time within 5 °C of actual Peak Temperature (tp) | 10-30 seconds | 20-40 seconds |
| Ramp-Down Rate | 6 °C/second max. | 6 °C/second max. |
| Time 25 °C to Peak Temperature | 6 minutes max. | 8 minutes max. |

Table 4. Classification Reflow Profiles (per IPC/JEDEC J-STD-020C, Table 5.2)

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

| Package Thickness | Volume mm³ <350 | Volume mm³ ≥350 | |
|-------------------|--------------------|--------------------|---|
| <2.5 mm | 240 +0/-5 °C | 225 +0/-5 °C | ٦ |
| ≥2.5 mm | 225 +0/-5 °C | 225 +0/-5 °C | ٦ |

Table 5. SnPb Eutectic Process - Package Peak Reflow Temperatures (per IPC/JEDEC J-STD-020C, Table 4.1)

| Package Thickness | Volume mm³ <350 | Volume mm³ 350-2000 | Volume mm ³ >2000 |
|-------------------|--------------------|------------------------|------------------------------|
| <1.6 mm | 260 + 0 °C * | 260 + 0 °C * | 260 + 0 °C * |
| 1.6 mm - 2.5 mm | 260 + 0 °C * | 250 + 0 °C * | 245 + 0 °C * |
| ≥2.5 mm | 250 + 0 °C * | 245 + 0 °C * | 245 + 0 °C * |

^{*} Tolerance: Process compatibility is up to and including the stated classification temperature (this means Peak reflow temperature + 0 °C. For example 260 °C + 0 °C) at the rated MSL level.

Table 6. Pb-free Process - Package Classification Reflow Temperatures (per IPC/JEDEC J-STD-020C, Table 4.2)

- Note 1: The profiling tolerance is +0 °C, -X °C (based on machine variation capability) whatever is required to control the profile process but at no time will it exceed -5 °C. Process compatibility at the peak reflow profile temperatures as defined in Table 4.2.
- Note 2: Package volume excludes external terminals (balls, bumps, lands, leads) and/or nonintegral heat sinks.
- Note 3: The maximum component temperature reached during reflow depends on package thickness and volume. The use of convection reflow processes reduces the thermal gradients between packages. However, thermal gradients due to differences in thermal mass of SMD packages may still exist.
- Note 4: Components intended for use in a "lead-free" assembly process shall be evaluated using the "lead-free" classification temperatures and profiles defined in Tables 4.1, 4.2 and 5.2 whether or not lead free.

Application Notice/Handling

- (4) Temperature and humidity conditions: less than 40°C and 70% RH.
- (5) Products should be used within 6 months.
- (6) The packaging material should be kept where no chlorine or sulfur exists in the air.
- (7) Do not touch the electrodes (soldering terminals) with fingers as this may lead to deterioration of solder ability
- (8) The use of tweezers or vacuum pick-ups is strongly recommended for individual components.
- (9) Bulk handling should ensure that abrasion and mechanical shock are minimized.